ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard  Form Typ  http://www.ipc.org/IPC-175x  Form Typ					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
Supplier Inform	ation														
Company name*	Company unique ID			1	Unique ID Authority					Response Date*					
nsemi												2023-06-08			
Contact Name			Title - Contact			]	Phone - Contact*					Email - Contact*			
Product-Env-Stewa	rds		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*		Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewa	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number		Mfr Item Number Mfr Ite		Mfr Item Name		Effective Da	te Version Manua		Manufactu	uring Site	e Weight*		UOM	Unit Type
		NCP3231BMNTXG Buck Conve		Buck Converter w	nverter with Integrated FETs		2023-06-08				9	8.65	mg	Each	
	Proccess Informatio			,										'	
Terminal Plating / Grid Array Material					J-STD-020 M	SL Rating		rocess Body Temperature   Max Time at Peak		Temperatu	ire Num	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed			CU Alloy 3				260   C   30			seconds 3					
Comments															
TTENTION: MSL	3 Rated item requires B	ake and Di	ry Pack (after	r electrical test)											
or more informatio	on regarding material con	nposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shave provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.0	mg	Supplier	Silicon (Si)	7440-21-3		8	mg
Die Attach Solder	12.0	mg	Supplier	Silver (Ag)	7440-22-4		0.3	mg
			A	Lead (Pb)	7439-92-1	7a	11.1	mg
			Supplier	Tin (Sn)	7440-31-5		0.6	mg
Lead Frame	50.35	mg	Supplier	Silver (Ag)	7440-22-4		1.3594	mg
			Supplier	Tin (Sn)	7440-31-5		0.1208	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0957	mg
			Supplier	Chromium (Cr)	7440-47-3		0.146	mg
			Supplier	Copper (Cu)	7440-50-8		48.628	mg
Mold Compound-Black	26.0	mg		Epoxy resin	proprietary data		1.222	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.6	mg
			Supplier	Carbon Black (C)	1333-86-4		0.026	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.93	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.222	mg
Plating	1.8	mg	Supplier	Tin (Sn)	7440-31-5		1.8	mg
Wire Bond - Au	0.5	mg	Supplier	Gold (Au)	7440-57-5		0.5	mg